Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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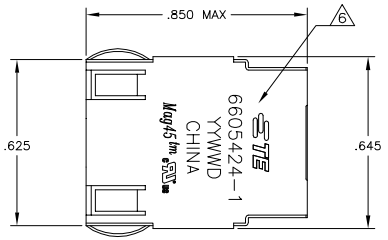
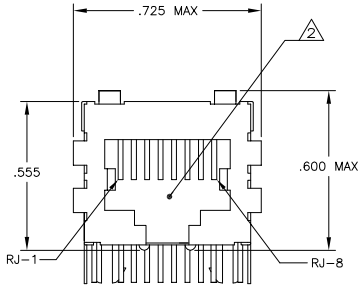
LOC	DIST
AA	22

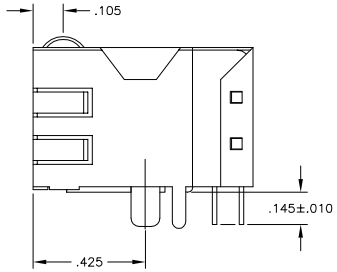
REVISIONS

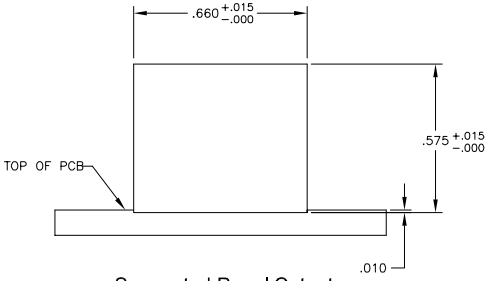
P	LTR	DESCRIPTION	DATE	DWN	APVD
	B1	REVISED PER ECO-11-005140	25MAR11	RK	HMR
	C	ECO-11-015766	30MAY2011	EL	LR

MECHANICAL:

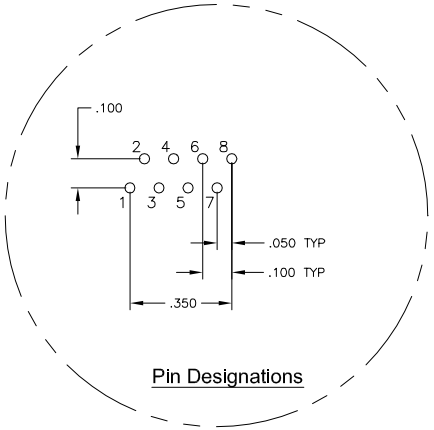




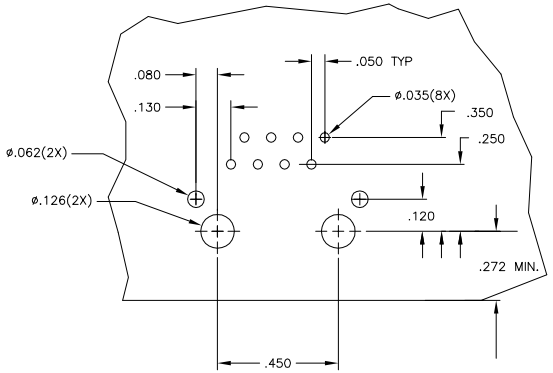




Suggested Panel Cutout



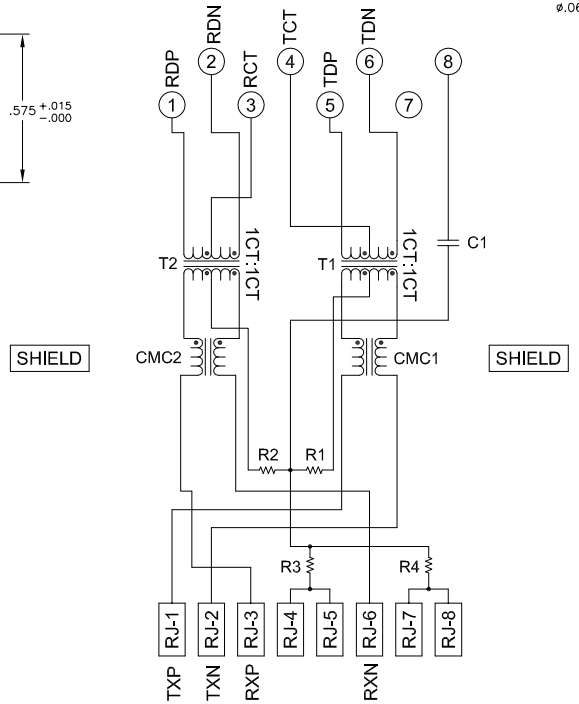
Pin Designations



Suggested PCB Layout
(Component Side)

ELECTRICAL:

426 SERIES MAGNETIC CIRCUIT 3 5



C1 = 1000 pF, 2kV CAPACITOR

R1-R4 = 75 OHMS, 1/16 W RESISTORS

1. MATERIALS:
HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER.
MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE.
SOLDERTAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.

2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

3. MAGNETICS
- IMPEDANCE: 100 OHMS
- TURNS RATIO (CHIP:CABLE): TX = 1:1, RX = 1:1
- OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
- PERFORMANCE @ 25°C:
  INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
  RETURN LOSS (RL): 18dB MIN FROM 0.5MHZ TO 30MHz
  18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
  12dB MIN FROM 60.1MHz TO 80MHz
  CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
  33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
  COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
- ISOLATION VOLTAGE:2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

4. OPERATING TEMPERATURE: FROM 0°C TO +70°C

5. INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORTS AUTO-MDI/MDIX.

6. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

7. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.

6605424-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: INCHES
TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± -
1 PLC ± -
2 PLC ± .010
3 PLC ± .005
4 PLC ± -
ANGLES ± -
MATERIAL 1
FINISH 1

DWN G. ATTADIA 08MAR2005 DOCK5
CHK D. FAROLE 08MAR2005
APVD D. FAROLE 08MAR2005
PRODUCT SPEC 108-2100
APPLICATION SPEC —
WEIGHT —

TE Connectivity

NAME 1X1 MAG45(TM), MODULAR JACK, 4N2 SCHEMATIC, 426 SERIES CIRCUIT, SHIELDED, DECOUPLING CAPACITOR, NO LEDS

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C-6605424	—

CUSTOMER DRAWING SCALE NTS SHEET 1 OF 1 REV C

4805 (3/11)